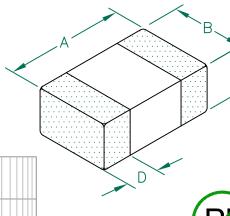
CPI0805H1R2R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:



D 0.50 [.020] ± 0.20[.008]



ELECTRICAL CHARACTERISTICS:									
	L (μΗ) @ 1MHz ± 20%	DCR ($\frac{\Omega}{2}$) ± 25%	l (Max)						
Nom	1.20	0.16							
Min	0.96	0.12							
Max	1.44	0.20	800mA						

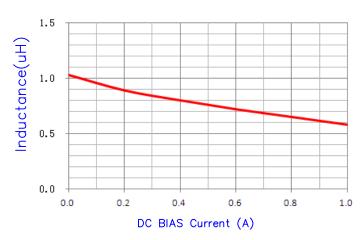
NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

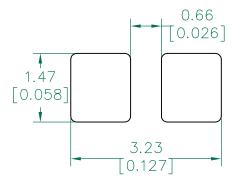
2.00 1.50 1.00 0.50 1.00 1.00 1.00 1.000

Frequency (MHz)

Ls vs DC BIAS Current

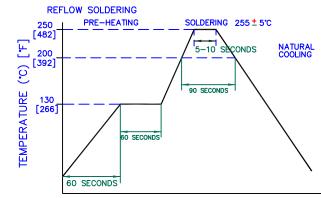


LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering. add 0.763 [0.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS





	DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird					
					Tech, and is loaned in confidence subject to return upon request			_	=	.■"
ı					with the understanding that no			2	ir(7
ĺ					copies shall be made without th written consent of Laird Tech. A			u		
İ					rights to design or invention are		_			
i					reserved.					
i	D	CHANGE PLASTIC TAPE TO PAPER TAPE	04/17/14	QU	PROJECT/PART NUMBER:		REV	PART TY	PE:	DRAWN BY:
ł	c	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	_	CPI0805H1R2R-10		D co		-FIRE QU	
		OPDATE LAIRD LOGO AND NOTES 5		_	CI 10003ITINZIN 10		_			
	B	Correct L tolerance	12/12/12	Qυ	DATE: 03/01/11 SC		SCALE: NTS		SHEET:	
	A	ORIGINAL DRAFT	03/01/11	QU		TOO		13		
	. ^ .									
	REV	DESCRIPTION	DATE	INT	CPI0805H1R2R-10-A	'``		-	1	of 1